

PCN Number:	20150731001		PCN Date:	08/12/2015										
Title:	Add Cu as Alternative Wire Base Metal for Selected Device(s)													
Customer Contact:	PCN Manager	Dept:	Quality Services											
Proposed 1st Ship Date:	11/12/2015	Estimated Sample Availability:	Date provided at sample request											
Change Type:														
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site									
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material									
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process									
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site									
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials									
				<input type="checkbox"/>	Wafer Fab Process									
PCN Details														
Description of Change:														
Texas Instruments is pleased to announce the qualification of Cu as an additional bond wire option for selected devices listed in "Product affected" section below. Devices will remain in current assembly facilities and there will be no other piece part changes:														
<table border="1"> <thead> <tr> <th>Pkg Family</th> <th>Current Wire</th> <th>Additional Wire</th> </tr> </thead> <tbody> <tr> <td>SOIC, VSSOP</td> <td>Au, 1.0mil</td> <td>Cu, 0.96 mil</td> </tr> <tr> <td>SOT</td> <td>Au, 0.9 / 1.0 mil</td> <td>Cu, 0.96 mil</td> </tr> </tbody> </table>						Pkg Family	Current Wire	Additional Wire	SOIC, VSSOP	Au, 1.0mil	Cu, 0.96 mil	SOT	Au, 0.9 / 1.0 mil	Cu, 0.96 mil
Pkg Family	Current Wire	Additional Wire												
SOIC, VSSOP	Au, 1.0mil	Cu, 0.96 mil												
SOT	Au, 0.9 / 1.0 mil	Cu, 0.96 mil												
Reason for Change:														
Continuity of supply. 1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties 2) Maximize flexibility within our Assembly/Test production sites. 3) Cu is easier to obtain and stock														
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):														
None														
Anticipated impact on Material Declaration														
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website .											
Changes to product identification resulting from this PCN:														
None														

Product Affected:

Device	Pkg Family	Device	Pkg Family
EMB1478MR/NOPB	SOIC	LP2985AIM5X-2.5/NOPB	SOT
EMB1478MRE/NOPB	SOIC	LP2985AIM5X-2.6/NOPB	SOT
EMB1478MRX/NOPB	SOIC	LP2985AIM5X-2.7/NOPB	SOT
EMB1498MF/NOPB	SOT	LP2985AIM5X-2.8/NOPB	SOT
EMB1498MFE/NOPB	SOT	LP2985AIM5X-2.9/NOPB	SOT
EMB1498MFX/NOPB	SOT	LP2985AIM5X-3.0/NOPB	SOT
LM4040BIM7-2.0/NOPB	SOT	LP2985AIM5X-3.1/NOPB	SOT
LM4040BIM7-2.5	SOT	LP2985AIM5X-3.3	SOT
LM4040BIM7-2.5/NOPB	SOT	LP2985AIM5X-3.3/E7002217	SOT
LM4040BIM7-5.0/NOPB	SOT	LP2985AIM5X-3.3/NOPB	SOT
LM4040BIM7X-2.5/NOPB	SOT	LP2985AIM5X-3.6/NOPB	SOT
LM4040CIM7-2.0/NOPB	SOT	LP2985AIM5X-3.8/NOPB	SOT
LM4040CIM7-2.5/NOPB	SOT	LP2985AIM5X-4.0/NOPB	SOT
LM4040CIM7X-2.5/NOPB	SOT	LP2985AIM5X-4.5/NOPB	SOT
LM4040DIM7-2.0/NOPB	SOT	LP2985AIM5X-5.0	SOT
LM4040DIM7-2.5/NOPB	SOT	LP2985AIM5X-5.0/NOPB	SOT
LM4040DIM7-5.0	SOT	LP2985AIM5X-5.7/NOPB	SOT
LM4040DIM7-5.0/NOPB	SOT	LP2985AIM5X-6.1/NOPB	SOT
LM4040EIM7-2.0/NOPB	SOT	LP2985IM5-1.8	SOT
LM4041BIM7-1.2	SOT	LP2985IM5-1.8/NOPB	SOT
LM4041BIM7-1.2/NOPB	SOT	LP2985IM5-2.0	SOT
LM4041BIM7X-1.2/NOPB	SOT	LP2985IM5-2.0/NOPB	SOT
LM4041CIM7-ADJ	SOT	LP2985IM5-2.5	SOT
LM4041CIM7-ADJ/NOPB	SOT	LP2985IM5-2.5/NOPB	SOT
LM4041CIM7X-1.2/NOPB	SOT	LP2985IM5-2.7/NOPB	SOT
LM4041CIM7X-ADJ	SOT	LP2985IM5-2.8/NOPB	SOT
LM4041CIM7X-ADJ/NOPB	SOT	LP2985IM5-2.9/NOPB	SOT
LM4041DIM7-1.2/NOPB	SOT	LP2985IM5-3.0/NOPB	SOT
LM4041DIM7-ADJ/NOPB	SOT	LP2985IM5-3.1/NOPB	SOT
LM4041DIM7X-1.2/NOPB	SOT	LP2985IM5-3.2/NOPB	SOT
LM4041DIM7X-ADJ/NOPB	SOT	LP2985IM5-3.3	SOT
LM4041EIM7-1.2/NOPB	SOT	LP2985IM5-3.3/NOPB	SOT
LM4041EIM7X-1.2/NOPB	SOT	LP2985IM5-3.5/NOPB	SOT
LMH6601MG/NOPB	SOT	LP2985IM5-3.6	SOT
LMH6601MGX/NOPB	SOT	LP2985IM5-3.6/NOPB	SOT
LMH6657MG	SOT	LP2985IM5-3.8	SOT
LMH6657MG/NOPB	SOT	LP2985IM5-3.8/NOPB	SOT
LMH6657MGX/NOPB	SOT	LP2985IM5-4.0/NOPB	SOT
LMS33460MG	SOT	LP2985IM5-4.5/NOPB	SOT
LMS33460MG/NOPB	SOT	LP2985IM5-5.0	SOT
LMV301MG/NOPB	SOT	LP2985IM5-5.0/NOPB	SOT
LMV301MGX	SOT	LP2985IM5-5.7/NOPB	SOT
LMV301MGX/NOPB	SOT	LP2985IM5-6.1/NOPB	SOT
LMV321M7	SOT	LP2985IM5X-1.8/NOPB	SOT
LMV321M7/J7001897	SOT	LP2985IM5X-2.0/NOPB	SOT
LMV321M7X	SOT	LP2985IM5X-2.5/NOPB	SOT
LMV321M7X/J7001898	SOT	LP2985IM5X-2.7/NOPB	SOT
LMV321M7X/NOPB	SOT	LP2985IM5X-2.8/NOPB	SOT
LMV331M7	SOT	LP2985IM5X-2.9/NOPB	SOT
LMV331M7/NOPB	SOT	LP2985IM5X-3.0/NOPB	SOT
LMV331M7X	SOT	LP2985IM5X-3.1/NOPB	SOT
LMV331M7X/NOPB	SOT	LP2985IM5X-3.3/NOPB	SOT
LMV341MG/NOPB	SOT	LP2985IM5X-3.3/S5001421	SOT
LMV341MGX/NOPB	SOT	LP2985IM5X-3.6/NOPB	SOT

LMV551MG/NOPB	SOT	LP2985IM5X-3.8/NOPB	SOT
LMV551MGX/NOPB	SOT	LP2985IM5X-4.0/NOPB	SOT
LMV601MG/NOPB	SOT	LP2985IM5X-4.5/NOPB	SOT
LMV601MGX/NOPB	SOT	LP2985IM5X-5.0	SOT
LMV611MG/NOPB	SOT	LP2985IM5X-5.0/NOPB	SOT
LMV611MGX/NOPB	SOT	LP2985IM5X-5.7/NOPB	SOT
LMV641MG/NOPB	SOT	LP2985IM5X-6.1/NOPB	SOT
LMV641MGE/NOPB	SOT	LP2986AIM-3.0/NOPB	SOIC
LMV641MGX/NOPB	SOT	LP2986AIM-3.3	SOIC
LMV651MG/NOPB	SOT	LP2986AIM-3.3/NOPB	SOIC
LMV651MGX/NOPB	SOT	LP2986AIM-5.0	SOIC
LMV7219M7	SOT	LP2986AIM-5.0/NOPB	SOIC
LMV7219M7/NOPB	SOT	LP2986AIMM-3.0/NOPB	VSSOP
LMV7219M7X	SOT	LP2986AIMM-3.3/NOPB	VSSOP
LMV7219M7X/NOPB	SOT	LP2986AIMM-5.0/NOPB	VSSOP
LMV721M7	SOT	LP2986AIMMX-3.0/NOPB	VSSOP
LMV721M7/NOPB	SOT	LP2986AIMMX-3.3/NOPB	VSSOP
LMV721M7X/NOPB	SOT	LP2986AIMMX-5.0/NOPB	VSSOP
LMV7235M7	SOT	LP2986AIMX-3.0/NOPB	SOIC
LMV7235M7/NOPB	SOT	LP2986AIMX-3.3/NOPB	SOIC
LMV7235M7X/NOPB	SOT	LP2986AIMX-5.0/NOPB	SOIC
LMV7239M7	SOT	LP2986IM-3.0/NOPB	SOIC
LMV7239M7/E7001398	SOT	LP2986IM-3.3	SOIC
LMV7239M7/HALF	SOT	LP2986IM-3.3/NOPB	SOIC
LMV7239M7/MESN	SOT	LP2986IM-5.0	SOIC
LMV7239M7/NOPB	SOT	LP2986IM-5.0/NOPB	SOIC
LMV7239M7X	SOT	LP2986IMM-3.0/NOPB	VSSOP
LMV7239M7X/E7002743	SOT	LP2986IMM-3.3	VSSOP
LMV7239M7X/HALF	SOT	LP2986IMM-3.3/NOPB	VSSOP
LMV7239M7X/MESN	SOT	LP2986IMM-5.0/NOPB	VSSOP
LMV7239M7X/NOPB	SOT	LP2986IMMX-3.0/NOPB	VSSOP
LMV7271MG	SOT	LP2986IMMX-3.3/NOPB	VSSOP
LMV7271MG/NOPB	SOT	LP2986IMMX-5.0/NOPB	VSSOP
LMV7271MGX/NOPB	SOT	LP2986IMX-3.0/NOPB	SOIC
LMV7275MG	SOT	LP2986IMX-3.3/E7002697	SOIC
LMV7275MGX/EMSN	SOT	LP2986IMX-3.3/NOPB	SOIC
LMV7275MGX/NOPB	SOT	LP2986IMX-5.0	SOIC
LMV7291MG	SOT	LP2986IMX-5.0/NAK2	SOIC
LMV7291MG/67	SOT	LP2986IMX-5.0/NOPB	SOIC
LMV7291MG/NOPB	SOT	LP2987AIMM-5.0/NOPB	VSSOP
LMV7291MGX/NOPB	SOT	LP2987AIMMX-5.0/NOPB	VSSOP
LMV771MG	SOT	LP2987AIMX-5.0/NOPB	SOIC
LMV771MG/HALF	SOT	LP2987IM-3.0/NOPB	SOIC
LMV771MG/NOPB	SOT	LP2987IM-3.3/NOPB	SOIC
LMV771MGX/NOPB	SOT	LP2987IM-5.0	SOIC
LMV821M7	SOT	LP2987IM-5.0/NOPB	SOIC
LMV821M7/NOPB	SOT	LP2987IMM-3.3/NOPB	VSSOP
LMV821M7X	SOT	LP2987IMM-5.0/NOPB	VSSOP
LMV821M7X/NOPB	SOT	LP2987IMMX-3.3/NOPB	VSSOP
LMV831MG/NOPB	SOT	LP2987IMMX-5.0/NOPB	VSSOP
LMV831MGE/NOPB	SOT	LP2987IMX-3.0/NOPB	SOIC
LMV831MGX/NOPB	SOT	LP2987IMX-5.0/NOPB	SOIC
LMV841MG/NOPB	SOT	LP2988AIM-5.0	SOIC
LMV841MGX/NOPB	SOT	LP2988AIM-5.0/NOPB	SOIC
LMV841MGX/S7002498	SOT	LP2988AIMM-2.8/NOPB	VSSOP
LMV851MG/NOPB	SOT	LP2988AIMM-3.0/NOPB	VSSOP
LMV851MGE/NOPB	SOT	LP2988AIMM-3.3/NOPB	VSSOP
LMV851MGX/NOPB	SOT	LP2988AIMM-5.0/NOPB	VSSOP

LMV861MG/NOPB	SOT	LP2988AIMMX-3.0/NOPB	VSSOP
LMV861MGE/NOPB	SOT	LP2988AIMMX-3.3/NOPB	VSSOP
LMV861MGX/NOPB	SOT	LP2988AIMMX-5.0/NOPB	VSSOP
LMV861MGX/S7002538	SOT	LP2988AIMX-3.3/NOPB	SOIC
LMV931MG	SOT	LP2988IM-5.0/NOPB	SOIC
LMV931MG/J7002117	SOT	LP2988IMM-2.8/NOPB	VSSOP
LMV931MG/NOPB	SOT	LP2988IMM-3.0/NOPB	VSSOP
LMV931MGX/J7001669	SOT	LP2988IMM-3.3/NOPB	VSSOP
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LP2980AIM5-3.0/NOPB	SOT	LP2989AIM-3.0/NOPB	SOIC
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LP2980AIM5X-2.5	SOT	LP2989AIMM-3.3/NOPB	VSSOP
LP2980AIM5X-2.5/NOPB	SOT	LP2989AIMM-5.0/NOPB	VSSOP
LP2980AIM5X-3.0	SOT	LP2989AIMMX-2.5/NOPB	VSSOP
LP2980AIM5X-3.0/NOPB	SOT	LP2989AIMMX-3.0/NOPB	VSSOP
LP2980AIM5X-3.3	SOT	LP2989AIMMX-3.3/NOPB	VSSOP
LP2980AIM5X-3.3/NOPB	SOT	LP2989AIMMX-5.0	VSSOP
LP2980AIM5X-4.7	SOT	LP2989AIMMX-5.0/NOPB	VSSOP
LP2980AIM5X-4.7/NOPB	SOT	LP2989AIMX-1.8/NOPB	SOIC
LP2980AIM5X-5.0	SOT	LP2989AIMX-2.5/E7002218	SOIC
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LP2980IM5-3.3/NOPB	SOT	LP2989IM-1.8/NOPB	SOIC
LP2980IM5-3.8/NOPB	SOT	LP2989IM-2.5	SOIC
LP2980IM5-4.7/NOPB	SOT	LP2989IM-2.5/NOPB	SOIC
LP2980IM5-5.0	SOT	LP2989IM-3.0/NOPB	SOIC
LP2980IM5-5.0/NOPB	SOT	LP2989IM-3.3	SOIC
LP2980IM5-ADJ	SOT	LP2989IM-3.3/NOPB	SOIC
LP2980IM5-ADJ/NOPB	SOT	LP2989IM-5.0	SOIC
LP2980IM5X-2.5/NOPB	SOT	LP2989IM-5.0/NOPB	SOIC
LP2980IM5X-3.0	SOT	LP2989IMM-2.8/NOPB	VSSOP
LP2980IM5X-3.0/NOPB	SOT	LP2989IMM-3.0/NOPB	VSSOP
LP2980IM5X-3.3	SOT	LP2989IMM-3.3/NOPB	VSSOP
LP2980IM5X-3.3/NOPB	SOT	LP2989IMM-5.0	VSSOP
LP2980IM5X-4.7/NOPB	SOT	LP2989IMM-5.0/NOPB	VSSOP
LP2980IM5X-5.0	SOT	LP2989IMMX-2.8/NOPB	VSSOP
LP2980IM5X-5.0/J5000350	SOT	LP2989IMMX-3.0/NOPB	VSSOP
LP2980IM5X-5.0/J7001473	SOT	LP2989IMMX-3.3/NOPB	VSSOP
LP2980IM5X-5.0/NOPB	SOT	LP2989IMMX-5.0	VSSOP
LP2980IM5X-ADJ	SOT	LP2989IMMX-5.0/NOPB	VSSOP
LP2980IM5X-ADJ/J7001048	SOT	LP2989IMX-1.8/NOPB	SOIC

LP2980IM5X-ADJ/NOPB	SOT	LP2989IMX-2.5/NOPB	SOIC
LP2980IM5X-ADJ/S7002499	SOT	LP2989IMX-3.0/NOPB	SOIC
LP2981AIM5-2.5	SOT	LP2989IMX-3.3	SOIC
LP2981AIM5-2.5/NOPB	SOT	LP2989IMX-3.3/NOPB	SOIC
LP2981AIM5-3.0/NOPB	SOT	LP2989IMX-5.0/NOPB	SOIC
LP2981AIM5-3.3	SOT	LP2992AIM5-1.5/NOPB	SOT
LP2981AIM5-3.3/NOPB	SOT	LP2992AIM5-1.8	SOT
LP2981AIM5-3.6	SOT	LP2992AIM5-1.8/NOPB	SOT
LP2981AIM5-3.6/NOPB	SOT	LP2992AIM5-2.5	SOT
LP2981AIM5-5.0	SOT	LP2992AIM5-2.5/NOPB	SOT
LP2981AIM5-5.0/NOPB	SOT	LP2992AIM5-3.3	SOT
LP2981AIM5X-3.0/NOPB	SOT	LP2992AIM5-3.3/NOPB	SOT
LP2981AIM5X-3.3	SOT	LP2992AIM5-5.0	SOT
LP2981AIM5X-3.3/E5000750	SOT	LP2992AIM5-5.0/NOPB	SOT
LP2981AIM5X-3.3/NOPB	SOT	LP2992AIM5X-1.5/NOPB	SOT
LP2981AIM5X-3.6/NOPB	SOT	LP2992AIM5X-1.8	SOT
LP2981AIM5X-5.0/NOPB	SOT	LP2992AIM5X-1.8/NOPB	SOT
LP2981IM5-2.5	SOT	LP2992AIM5X-2.5/NOPB	SOT
LP2981IM5-2.5/NOPB	SOT	LP2992AIM5X-3.3/NOPB	SOT
LP2981IM5-3.0/NOPB	SOT	LP2992AIM5X-5.0/NOPB	SOT
LP2981IM5-3.3	SOT	LP2992IM5-1.5/NOPB	SOT
LP2981IM5-3.3/NOPB	SOT	LP2992IM5-1.8	SOT
LP2981IM5-3.6/NOPB	SOT	LP2992IM5-1.8/NOPB	SOT
LP2981IM5-5.0	SOT	LP2992IM5-2.5	SOT
LP2981IM5-5.0/NOPB	SOT	LP2992IM5-2.5/NOPB	SOT
LP2981IM5X-3.0/NOPB	SOT	LP2992IM5-3.0	SOT
LP2981IM5X-3.3	SOT	LP2992IM5-3.0/NOPB	SOT
LP2981IM5X-3.3/NOPB	SOT	LP2992IM5-3.3	SOT
LP2981IM5X-3.6/NOPB	SOT	LP2992IM5-3.3/NOPB	SOT
LP2981IM5X-5.0	SOT	LP2992IM5-5.0	SOT
LP2981IM5X-5.0/NOPB	SOT	LP2992IM5-5.0/NOPB	SOT
LP2982AIM5-3.0/NOPB	SOT	LP2992IM5X-1.5/NOPB	SOT
LP2982AIM5-3.3	SOT	LP2992IM5X-1.8/NOPB	SOT
LP2982AIM5-3.3/NOPB	SOT	LP2992IM5X-2.5	SOT
LP2982AIM5-5.0	SOT	LP2992IM5X-2.5/NOPB	SOT
LP2982AIM5-5.0/NOPB	SOT	LP2992IM5X-3.3/NOPB	SOT
LP2982AIM5X-3.0/NOPB	SOT	LP2992IM5X-5.0/NOPB	SOT
LP2982AIM5X-3.3/NOPB	SOT	LP3878MR-ADJ	SOIC
LP2982AIM5X-5.0/NOPB	SOT	LP3878MR-ADJ/NOPB	SOIC
LP2982AIM5X-5.0/S7003010	SOT	LP3878MRX-ADJ/J7002929	SOIC
LP2982IM5-3.0/NOPB	SOT	LP3878MRX-ADJ/NOPB	SOIC
LP2982IM5-3.3/NOPB	SOT	LP3879MR-1.0/NOPB	SOIC
LP2982IM5-5.0/NOPB	SOT	LP3879MR-1.2	SOIC
LP2982IM5X-3.0/NOPB	SOT	LP3879MR-1.2/NOPB	SOIC
LP2982IM5X-3.3/NOPB	SOT	LP3879MRX-1.0/NOPB	SOIC
LP2982IM5X-5.0/NOPB	SOT	LP3879MRX-1.2/NOPB	SOIC
LP2983AIM5-1.0/NOPB	SOT	LP5951MG-1.3/NOPB	SOT
LP2983AIM5-1.2/NOPB	SOT	LP5951MG-1.5	SOT
LP2983AIM5X-1.0/NOPB	SOT	LP5951MG-1.5/NOPB	SOT
LP2983AIM5X-1.2/NOPB	SOT	LP5951MG-1.8/NOPB	SOT
LP2983IM5-1.0/NOPB	SOT	LP5951MG-2.0/NOPB	SOT
LP2983IM5-1.2	SOT	LP5951MG-2.5/NOPB	SOT
LP2983IM5-1.2/NOPB	SOT	LP5951MG-2.8/NOPB	SOT
LP2983IM5X-1.0/NOPB	SOT	LP5951MG-3.0/NOPB	SOT
LP2983IM5X-1.2/NOPB	SOT	LP5951MG-3.3/NOPB	SOT
LP2985AIM5-1.5/NOPB	SOT	LP5951MG-3.7/NOPB	SOT
LP2985AIM5-1.8/NOPB	SOT	LP5951MGX-1.3/NOPB	SOT
LP2985AIM5-2.0/NOPB	SOT	LP5951MGX-1.5/NOPB	SOT

LP2985AIM5-2.5/NOPB	SOT	LP5951MGX-1.8/NOPB	SOT
LP2985AIM5-2.7/NOPB	SOT	LP5951MGX-2.0/NOPB	SOT
LP2985AIM5-2.8	SOT	LP5951MGX-2.5/NOPB	SOT
LP2985AIM5-2.8/NOPB	SOT	LP5951MGX-2.8/NOPB	SOT
LP2985AIM5-2.9/NOPB	SOT	LP5951MGX-3.0/NOPB	SOT
LP2985AIM5-3.0	SOT	LP5951MGX-3.3/NOPB	SOT
LP2985AIM5-3.0/NOPB	SOT	LP5951MGX-3.7/NOPB	SOT
LP2985AIM5-3.1/NOPB	SOT	LPV321M7	SOT
LP2985AIM5-3.3	SOT	LPV321M7/NOPB	SOT
LP2985AIM5-3.3/NOPB	SOT	LPV321M7X	SOT
LP2985AIM5-3.6	SOT	LPV321M7X/NOPB	SOT
LP2985AIM5-3.6/NOPB	SOT	LPV511MG/NOPB	SOT
LP2985AIM5-3.8/NOPB	SOT	LPV511MGX/NOPB	SOT
LP2985AIM5-4.0/NOPB	SOT	LPV521MG/NOPB	SOT
LP2985AIM5-4.5/NOPB	SOT	LPV521MGE/NOPB	SOT
LP2985AIM5-5.0	SOT	LPV521MGX/NOPB	SOT
LP2985AIM5-5.0/NOPB	SOT	LPV7215MG/NOPB	SOT
LP2985AIM5-5.7/NOPB	SOT	LPV7215MGX/NOPB	SOT
LP2985AIM5-6.1/NOPB	SOT	LPV7217MG/NOPB	SOT
LP2985AIM5X-1.8/E7002823	SOT	LPV7217MGX/NOPB	SOT
LP2985AIM5X-1.8/NOPB	SOT	SM73308MG/NOPB	SOT
LP2985AIM5X-2.0/NOPB	SOT	SM73308MGE/NOPB	SOT
LP2985AIM5X-2.5	SOT	SM73308MGX/NOPB	SOT
LP2985AIM5X-2.5/E7002216	SOT		

Qualification Report

Qualification of 0.96 mils Cu wires on SC70 (DCK 5 and 6 Pin) Package at TIEMA

Attributes	Qual Device: LMV7275MG/NOPB	Supporting QBS: LM4041AIM3-1.2 (TL)	Supporting QBS: LM4041AIM3-1.2 (TL)	Supporting QBS: LM3420AM5-8.4 (TL)
Assembly Site	TIEM-MALACCA	TIEM-MALACCA	TIEM-MALACCA	TIEM-MALACCA
Package Family	SC70	SOT23	SOT23	SOT23
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Site	MFAB	GFAB	GFAB	GFAB
Wafer Fab Process	CMOS7	LFAST	LFAST	LFAST

- QBS: Qual By Similarity
- Qual Device LMV7275MG/NOPB is qualified at LEVEL1-260CG

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LMV7275MG/NOPB	Supporting QBS: LM4041AIM3-1.2 (TL)	Supporting QBS: LM4041AIM3-1.2 (TL)
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/120/0	3/119/0
HAST	Biased HAST, 130C/85%RH	192 Hours	-	3/120/0	
AC	Autoclave 121C	96 Hours	-	3/240/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	1/80/0	-	-
TC	Temperature Cycle, -65/150C	1000 Cycles	-	3/240/0	-
HTSL	High Temp Storage Bake 150C	500 Hours	1/80/0	2/160/0	1/79/0
HTSL	High Temp Storage Bake 150C	1000 Hours	0/80	2/160/0	1/79/0
MQ	Manufacturability (Assembly)		1/pass	1/pass	1/pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:
 Qualified Pb-Free(SMT) and Green

Qualification Report

0.96 mil Cu wire qual for SOT23 Packages

Product Attributes

Attributes	Qual Device: LM4041AIM3-1.2	Qual Device: LP3985IM5X-5.0	Qual Device: LMC7101AIM5NOPB	Qual Device: LM431CCM3NOPB
Assembly Site	TIEMA	TIEMA	TIEMA	TIEMA
Package Family	SOT	SOT	SOT	SOT
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	GFAB	MFAB	GFAB	GFAB
Wafer Fab Process	BPLFAST-1	CMOS7	P2CMOS	SLM

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LM4041AIM3-1.2	Qual Device: LP3985IM5X-5.0	Qual Device: LMC7101AIM5NOPB	Qual Device: LM431CCM3NOPB
PC	PreCon Level 1	Level 1-260C	3/693/0	3/462/0	3/693/0	3/462/0
HAST	Biased HAST, 130C/85%RH	96/hrs. @130C	3/231/0	-	3/231/0	-
AC	Autoclave 121C	96HRS	3/231/0	3/231/0	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	TMCL500X	3/231/0	3/231/0	3/231/0	3/231/0
HTSL	High Temp Storage Bake 150C	1000 hrs. @150C	1/77/0	-	1/77/0	1/77/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass	Pass
DPA	Destructive Physical Analysis Post 500 Temp Cycle	x-section and de process to examine assembly robustness, Check for stich bond and bond pad integrity	3/15/0	3/15/0	3/15/0	3/15/0
YLD	FTY and Bin Summary	Compare against baseline	Pass	Pass	Pass	Pass

Qualification Report

0.96 mil Cu wire qual for SOIC Packages

Product Attributes

Attributes	Qual Device: DS90CP22MXA1CL	Qual Device: LMV324MX	Qual Device: LP2995MXNOPB	Qual Device: LMC6482AIM/NOPB
Assembly Site	TIEMA	TIEMA	TIEMA	TIEMA
Package Family	SOIC	SOIC	SOIC	SOIC
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	MFAB	MFAB	MFAB	GFAB
Wafer Fab Process	CMOS7	CS80	CS65	P2CMOS

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: DS90CP22MXA1CL	Qual Device: LMV324MX	Qual Device: LP2995MXNOPB	Qual Device: LMC6482AIM/NOPB
PC	PreCon Level 1	Level 1-260C	3/462/0	-	3/462/0	3/693/0
HAST	Biased HAST, 130C/85%RH	96/hrs. @ 130C	-	-	-	3/231/0
AC	Autoclave 121C	96HRS	3/231/0	-	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	TMCL500X	3/231/0	-	3/231/0	3/231/0
HTSL	High Temp Storage Bake 150C	1000 hrs. @ 150C	-	-	-	1/77/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	-	Pass	Pass	Pass
DPA	Destructive Physical Analysis Post 500 Temp Cycle	x-section and de process to examine assembly robustness, Check for stich bond and bond pad integrity	3/15/0	-	3/15/0	3/15/0
YLD	FTY and Bin Summary	Compare against baseline	-	Pass	Pass	Pass

Qualification Report

0.96 mil Cu wire qual for VSSOP & TSSOP Packages

Product Attributes

Attributes	Qual Device: LMV852MMX	Qual Device: LMC6482IMM	Qual Device: LM93CIMT	Qual Device: LM5642MHX
Assembly Site	TIEMA	TIEMA	TIEMA	TIEMA
Package Family	VSSOP	VSSOP	TSSOP	TSSOP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	MFAB	GFAB	MFAB	MFAB
Wafer Fab Process	CMOS7	P2CMOS	CMOS7	ABCD150

Qualification Results

*Data Displayed as: Number of lots / Total sample size /
Total failed*

Type	Test Name / Condition	Duration	Qual Device: LMV852MMX	Qual Device: LMC6482IMM	Qual Device: LM93CIMT	Qual Device: LM5642MHX
PC	PreCon Level 1	Level 1- 260C	3/462/0	3/462/0	-	3/231/0
PC	PreCon Level 2	Level 2- 260C	-	-	3/693/0	-
HAST	Biased HAST, 130C/85%RH	96/hrs. @130C	-	-	3/231/0	-
AC	Autoclave 121C	96HRS	3/231/0	3/231/0	3/231/0	-
TC	Temperature Cycle, -65/150C	TMCL500X	3/231/0	3/231/0	3/231/0	3/231/0
HTSL	High Temp Storage Bake 150C	1000 hrs. @150C	-	-	1/77/0	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	-	-
DPA	Destructive Physical Analysis Post 500 Temp Cycle	x-section and de process to examine assembly robustness, Check for stich bond and bond pad integrity	3/15/0	3/15/0	-	3/15/0
YLD	FTY and Bin Summary	Compare against baseline	Pass	Pass	-	-

Qualification Report

0.96 mil Cu wire qual for TSSOP Packages

Product Attributes

Attributes	Qual Device: LMH0346MH	Qual Device: LM5037MT	Qual Device: LM3657MH/NOPB	Qual Device: SCANSTA111MTX
Assembly Site	TIEMA	TIEMA	TIEMA	TIEMA
Package Family	TSSOP	TSSOP	TSSOP	TSSOP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	MFAB	GFAB	MFAB	MFAB
Wafer Fab Process	BICMOS8B+	ABCD150	CMOS7	CMOS7

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LMH0346MH	Qual Device: LM5037MT	Qual Device: LM3657MH/NOPB	Qual Device: SCANSTA111MTX
PC	PreCon Level 1	Level 1-260C	-	3/693/0	3/462/0	-
PC	PreCon Level 2	Level 2-260C	-	-	-	3/462/0
PC	PreCon Level 3	Level 3-260C	3/231/0	-	-	-
THBT	THBT 85C, 85%RH	1000/hrs. @85C	-	3/231/0	-	-
AC	Autoclave 121C	96HRS	-	3/231/0	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	TMCL500X	3/231/0	3/231/0	3/231/0	3/231/0
HTSL	High Temp Storage Bake 150C	1000 hrs. @150C	-	1/77/0	-	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass	Pass
DPA	Destructive Physical Analysis Post 500 Temp Cycle	x-section and de process to examine assembly robustness, Check for stich bond and bond pad integrity	3/15/0	3/15/0	3/15/0	3/15/0
YLD	FTY and Bin Summary	Compare against baseline	Pass	Pass	Pass	Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

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